



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-01
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	RVW8*UI69AC5	A	ZS1A	2017-06-01
Amount	UoM	Unit type	ST ECOPACK Grade	
6.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ating is used or other bulk terminati	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOT	2x1.26x0.93	5	gull wing	
Comment	Package: W8 SOT 323 5LDS; MDF valid for LDK130C-R			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RVW8*UI69AC5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.287	mg	supplier	die	Silicon (Si)	7440-21-3		0.268	mg	933798	44667
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	13937	667
				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	10453	500
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	3484	167
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	24390	1167
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.004	mg	13937	667
Leadframe	Copper and its alloy	1.828	mg	Supplier	Alloy	Copper (Cu)	7440-50-8		1.762	mg	963895	293667
				Supplier	Alloy	Iron (Fe)	7439-89-6		0.041	mg	22429	6833
				Supplier	Alloy	Zinc (Zn)	7440-66-6		0.002	mg	1094	333
				Supplier	metallization	Nickel (Ni)	7440-02-0		0.021	mg	11488	3500
				Supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	1094	333
Die Attach	Other Organic Material	0.066	mg	Supplier	Glue	Silver (Ag)	7440-22-4		0.053	mg	803030	8833
				Supplier	Glue	Carbocyclic Acrylates	Proprietary		0.007	mg	106061	1167
				Supplier	Glue	Bismaleimide resin	Proprietary		0.002	mg	30303	333
				Supplier	Glue	2-preponic acid, 2-methyl	68586-19-6		0.002	mg	30303	333
				Supplier	Glue	Additive	proprietary		0.002	mg	30303	333
Bonding Wire	Precious metals	0.022	mg	Supplier	Bonding Wire	Gold (Au)	7440-57-5		0.022	mg	1000000	3667
Encapsulation	Other Organic Material	3.796	mg	Supplier	Molding Compound	Epoxy Resin-1	Proprietary		0.114	mg	30032	19000
				Supplier	Molding Compound	Epoxy Resin-2	25068-38-6		0.114	mg	30032	19000
				Supplier	Molding Compound	Phenol resin	29690-82-2		0.170	mg	44784	28333
				Supplier	Molding Compound	Silica	60676-86-0		3.314	mg	873024	552333
				Supplier	Molding Compound	Carbon Black	1333-86-4		0.008	mg	2107	1333
Supplier	Molding Compound	Others	Proprietary		0.076	mg	20021	12667				